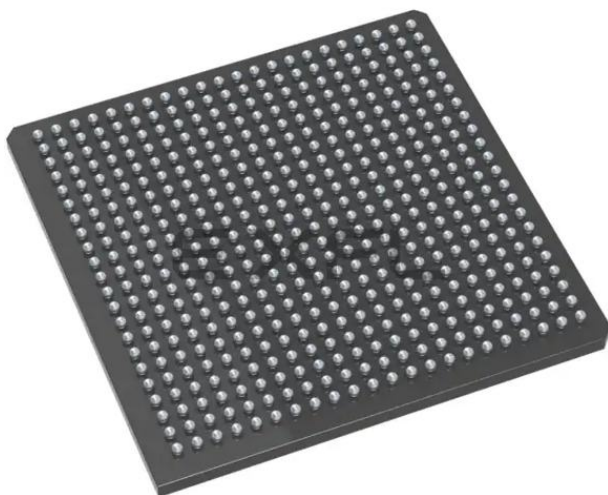




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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Active
Number of LABs/CLBs	-
Number of Logic Elements/Cells	-
Total RAM Bits	147456
Number of I/O	300
Number of Gates	1000000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 125°C (TA)
Package / Case	484-BGA
Supplier Device Package	484-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/a3p1000-fg484t

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Advanced Architecture

The proprietary Automotive ProASIC3 architecture provides granularity comparable to standard-cell ASICs. The Automotive ProASIC3 device consists of five distinct and programmable architectural features (Figure 1-1 and Figure 1-2 on page 1-4):

- FPGA VersaTiles
- Dedicated FlashROM
- Dedicated SRAM memory
- Extensive CCCs and PLLs
- Advanced I/O structure

The FPGA core consists of a sea of VersaTiles. Each VersaTile can be configured as a three-input logic function, a D-flip-flop (with or without enable), or a latch by programming the appropriate flash switch interconnections. The versatility of the Automotive ProASIC3 core tile as either a three-input lookup table (LUT) equivalent or a D-flip-flop/latch with enable allows for efficient use of the FPGA fabric. The VersaTile capability is unique to the Microsemi ProASIC family of third-generation-architecture flash FPGAs. VersaTiles are connected with any of the four levels of routing hierarchy. Flash switches are distributed throughout the device to provide nonvolatile, reconfigurable interconnect programming. Maximum core utilization is possible for virtually any design.

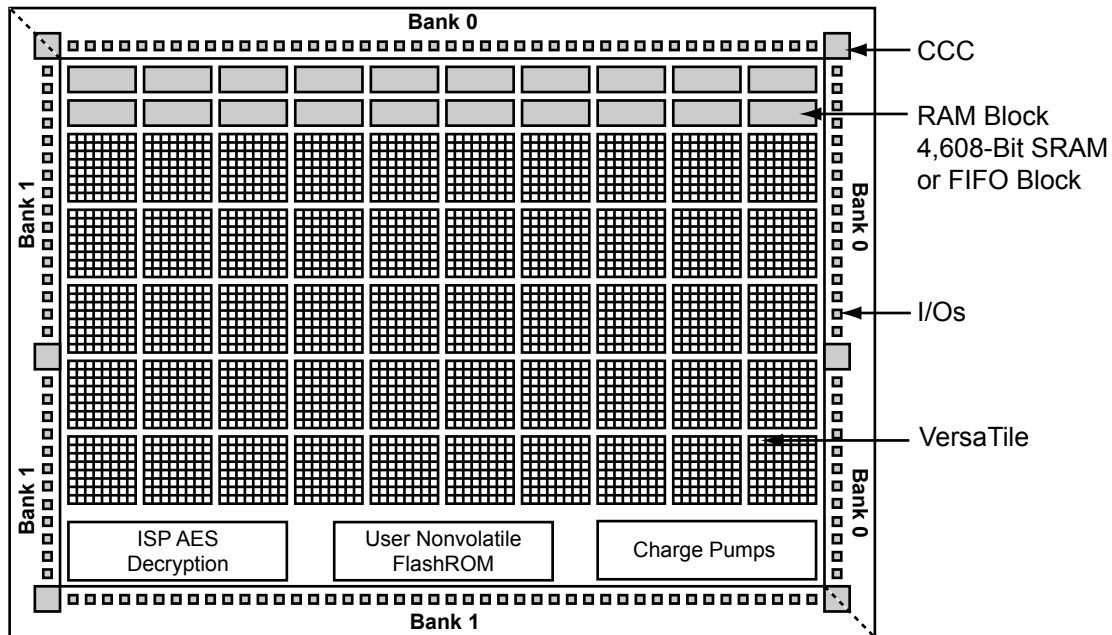


Figure 1-1 • Automotive ProASIC3 Device Architecture Overview with Two I/O Banks (A3P060 and A3P125)

Timing Characteristics

Table 2-35 • 3.3 V LVTTTL / 3.3 V LVCMOS High Slew

Automotive-Case Conditions: $T_J = 135^{\circ}\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 3.0\text{ V}$
Applicable to Advanced I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
4 mA	STD	0.64	8.56	0.05	1.14	0.46	8.72	7.37	1.46	1.42	11.22	9.866	ns
	-1	0.55	7.28	0.04	0.97	0.39	7.42	6.27	1.46	1.42	9.54	8.393	ns
6 mA	STD	0.64	5.49	0.05	1.14	0.46	5.59	4.55	1.65	1.74	8.09	7.05	ns
	-1	0.55	4.67	0.04	0.97	0.39	4.75	3.87	1.65	1.74	6.88	5.997	ns
8 mA	STD	0.64	5.49	0.05	1.14	0.46	5.59	4.55	1.65	1.74	8.09	7.05	ns
	-1	0.55	4.67	0.04	0.97	0.39	4.75	3.87	1.65	1.74	6.88	5.997	ns
12 mA	STD	0.64	3.95	0.05	1.14	0.46	4.02	1.56	3.59	1.94	6.52	2.795	ns
	-1	0.55	3.36	0.04	0.97	0.39	3.42	1.56	3.05	1.94	5.55	2.797	ns
16 mA	STD	0.64	3.73	0.05	1.14	0.46	1.84	1.42	3.65	4.11	3.05	2.651	ns
	-1	0.55	3.17	0.04	0.97	0.39	1.84	1.42	3.10	3.50	3.05	2.653	ns
24 mA	STD	0.64	3.44	0.05	1.14	0.46	1.70	1.17	3.72	4.54	2.91	2.405	ns
	-1	0.55	2.92	0.04	0.97	0.39	1.70	1.17	3.16	3.86	2.91	2.407	ns

Notes:

- Software default selection highlighted in gray.
- For specific junction temperature and voltage supply levels, refer to [Table 2-5 on page 2-5](#) for derating values.

Table 2-36 • 3.3 V LVTTTL / 3.3 V LVCMOS Low Slew

Automotive-Case Conditions: $T_J = 135^{\circ}\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 3.0\text{ V}$
Applicable to Advanced I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
4 mA	STD	0.64	11.47	0.05	1.14	0.46	11.68	9.95	1.46	1.33	14.18	12.449	ns
	-1	0.55	9.75	0.04	0.97	0.39	9.94	8.46	1.46	1.33	12.06	10.59	ns
6 mA	STD	0.64	8.13	0.05	1.14	0.46	8.28	7.03	1.65	1.65	10.79	9.526	ns
	-1	0.55	6.92	0.04	0.97	0.39	7.05	5.98	1.65	1.65	9.17	8.103	ns
8 mA	STD	0.64	8.13	0.05	1.14	0.46	8.28	7.03	1.65	1.65	10.79	9.526	ns
	-1	0.55	6.92	0.04	0.97	0.39	7.05	5.98	1.65	1.65	9.17	8.103	ns
12 mA	STD	0.64	6.24	0.05	1.14	0.46	6.36	5.45	1.77	1.85	8.86	7.946	ns
	-1	0.55	5.31	0.04	0.97	0.39	5.41	4.63	1.77	1.85	7.53	6.76	ns
16 mA	STD	0.64	5.82	0.05	1.14	0.46	5.93	5.10	1.80	1.90	8.43	7.604	ns
	-1	0.55	4.95	0.04	0.97	0.39	5.04	4.34	1.80	1.90	7.17	6.468	ns
24 mA	STD	0.64	5.42	0.05	1.14	0.46	5.52	5.08	1.83	2.10	8.02	7.581	ns
	-1	0.55	4.61	0.04	0.97	0.39	4.70	4.32	1.83	2.11	6.82	6.449	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-5 on page 2-5](#) for derating values.

Table 2-50 • 2.5 V LVCMOS High Slew

Automotive-Case Conditions: $T_J = 115^{\circ}\text{C}$, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 2.3 V
Applicable to Advanced I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	STD	0.63	9.37	0.05	1.40	0.45	8.47	9.37	1.43	1.21	10.89	11.79	ns
	-1	0.53	7.97	0.04	1.19	0.38	7.21	7.97	1.43	1.21	9.27	10.03	ns
6 mA	STD	0.63	5.59	0.05	1.40	0.45	5.45	5.59	1.63	1.57	7.87	8.01	ns
	-1	0.53	4.75	0.04	1.19	0.38	4.63	4.75	1.63	1.57	6.69	6.81	ns
12 mA	STD	0.63	3.85	0.05	1.40	0.45	3.92	3.71	1.77	1.80	6.34	6.13	ns
	-1	0.53	3.28	0.04	1.19	0.38	3.34	3.16	1.77	1.80	5.39	5.22	ns
16 mA	STD	0.63	3.63	0.05	1.40	0.45	1.79	1.64	3.64	3.84	2.96	2.83	ns
	-1	0.53	3.08	0.04	1.19	0.38	1.79	1.64	3.09	3.27	2.96	2.83	ns
24 mA	STD	0.63	3.34	0.05	1.40	0.45	1.65	1.31	3.72	4.32	2.82	2.50	ns
	-1	0.53	2.84	0.04	1.19	0.38	1.65	1.31	3.16	3.68	2.82	2.50	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-5 on page 2-5](#) for derating values.

Table 2-51 • 2.5 V LVCMOS Low Slew

Automotive-Case Conditions: $T_J = 115^{\circ}\text{C}$, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 2.3 V
Applicable to Advanced I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	STD	0.63	11.73	0.05	1.40	0.45	12.14	12.33	1.43	1.16	14.55	14.75	ns
	-1	0.53	9.98	0.04	1.19	0.38	10.32	10.49	1.43	1.16	12.38	12.55	ns
6 mA	STD	0.63	7.97	0.05	1.40	0.45	8.77	8.45	1.63	1.51	11.19	10.87	ns
	-1	0.53	6.78	0.04	1.19	0.38	7.46	7.19	1.63	1.52	9.52	9.25	ns
12 mA	STD	0.63	6.68	0.05	1.40	0.45	6.81	6.40	1.77	1.74	9.23	8.82	ns
	-1	0.53	5.69	0.04	1.19	0.38	5.79	5.45	1.77	1.74	7.85	7.50	ns
16 mA	STD	0.63	6.24	0.05	1.40	0.45	6.35	5.98	1.80	1.80	8.77	8.40	ns
	-1	0.53	5.30	0.04	1.19	0.38	5.40	5.08	1.80	1.80	7.46	7.14	ns
24 mA	STD	0.63	5.96	0.05	1.40	0.45	5.95	5.96	1.84	2.03	8.37	8.38	ns
	-1	0.53	5.07	0.04	1.19	0.38	5.06	5.07	1.84	2.03	7.12	7.12	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-5 on page 2-5](#) for derating values.

Timing Characteristics

Table 2-57 • 1.8 V LVC MOS High Slew

Automotive-Case Conditions: $T_J = 135^{\circ}\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 2.3\text{ V}$
Applicable to Advanced I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	STD	0.64	13.26	0.05	1.36	0.46	10.22	13.26	1.53	0.90	12.72	15.764	ns
	-1	0.55	11.28	0.04	1.16	0.39	8.69	11.28	1.53	0.90	10.82	13.41	ns
4 mA	STD	0.64	7.73	0.05	1.36	0.46	6.55	7.73	1.78	1.54	9.05	10.232	ns
	-1	0.55	6.58	0.04	1.16	0.39	5.58	6.58	1.78	1.54	7.70	8.704	ns
6 mA	STD	0.64	4.97	0.05	1.36	0.46	4.67	4.97	1.95	1.83	7.17	7.472	ns
	-1	0.55	4.23	0.04	1.16	0.39	3.98	4.23	1.95	1.83	6.10	6.356	ns
8 mA	STD	0.64	4.39	0.05	1.36	0.46	4.39	4.39	1.99	1.91	6.89	6.888	ns
	-1	0.55	3.73	0.04	1.16	0.39	3.74	3.73	1.99	1.91	5.86	5.859	ns
12 mA	STD	0.64	3.95	0.05	1.36	0.46	1.95	1.68	4.14	4.56	3.16	2.915	ns
	-1	0.55	3.36	0.04	1.16	0.39	1.95	1.68	3.52	3.88	3.16	2.918	ns
16 mA	STD	0.64	3.95	0.05	1.36	0.46	1.95	1.68	4.14	4.56	3.16	2.915	ns
	-1	0.55	3.36	0.04	1.16	0.39	1.95	1.68	3.52	3.88	3.16	2.918	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-5 on page 2-5](#) for derating values.

Table 2-93 • Input Data Register Propagation Delays
Automotive-Case Conditions: $T_J = 115^{\circ}\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$

Parameter	Description	–1	Std.	Units
t_{CLKQ}	Clock-to-Q of the Input Data Register	0.29	0.34	ns
t_{ISUD}	Data Setup Time for the Input Data Register	0.31	0.37	ns
t_{IHD}	Data Hold Time for the Input Data Register	0.00	0.00	ns
t_{ISUE}	Enable Setup Time for the Input Data Register	0.44	0.52	ns
t_{IHE}	Enable Hold Time for the Input Data Register	0.00	0.00	ns
t_{CLR2Q}	Asynchronous Clear-to-Q of the Input Data Register	0.54	0.64	ns
t_{PRE2Q}	Asynchronous Preset-to-Q of the Input Data Register	0.54	0.64	ns
t_{REMCLR}	Asynchronous Clear Removal Time for the Input Data Register	0.00	0.00	ns
t_{RECCLR}	Asynchronous Clear Recovery Time for the Input Data Register	0.27	0.31	ns
t_{REMPRE}	Asynchronous Preset Removal Time for the Input Data Register	0.00	0.00	ns
t_{RECPRE}	Asynchronous Preset Recovery Time for the Input Data Register	0.27	0.31	ns
t_{WCLR}	Asynchronous Clear Minimum Pulse Width for the Input Data Register	0.25	0.30	ns
t_{WPRE}	Asynchronous Preset Minimum Pulse Width for the Input Data Register	0.25	0.30	ns
t_{CKMPWH}	Clock Minimum Pulse Width High for the Input Data Register	0.41	0.48	ns
t_{CKMPWL}	Clock Minimum Pulse Width Low for the Input Data Register	0.37	0.43	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-5 on page 2-5](#) for derating values.

DDR Module Specifications

Input DDR Module

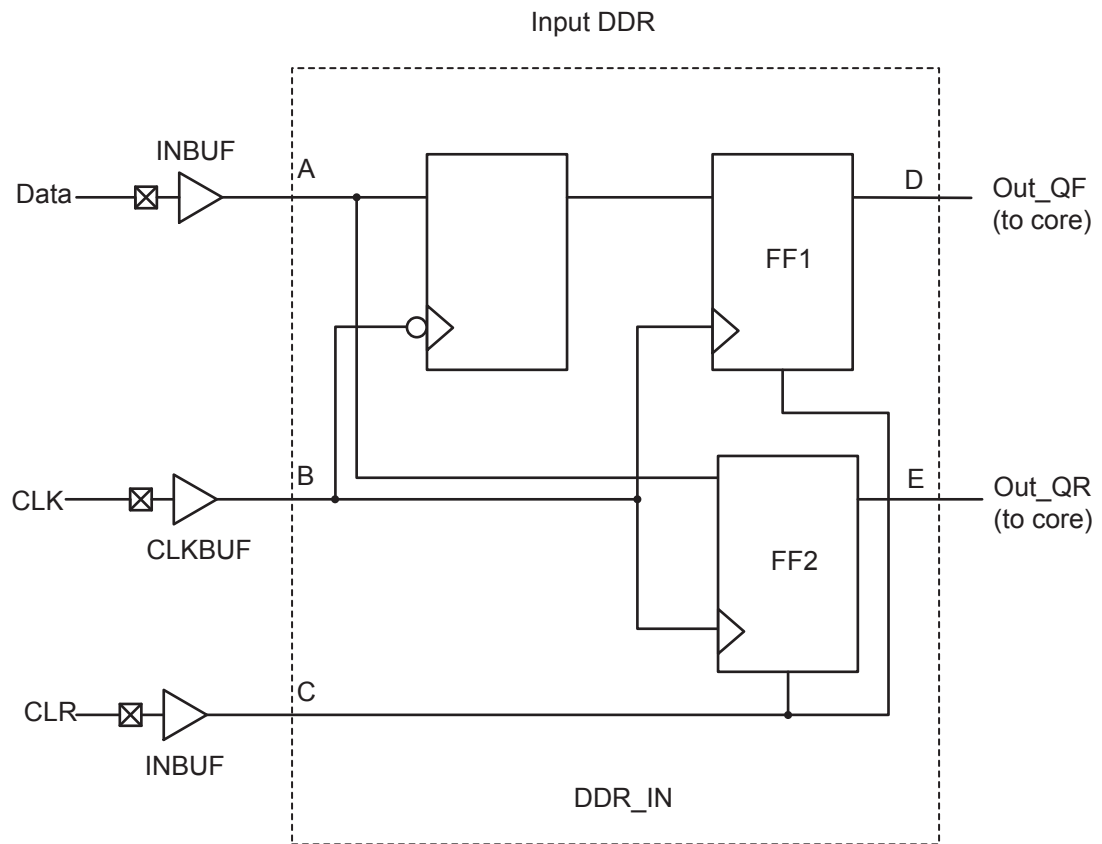


Figure 2-20 • Input DDR Timing Model

Table 2-98 • Parameter Definitions

Parameter Name	Parameter Definition	Measuring Nodes (from, to)
t_{DDRCLKQ1}	Clock-to-Out Out_QR	B, D
t_{DDRCLKQ2}	Clock-to-Out Out_QF	B, E
t_{DDRISUD}	Data Setup Time of DDR Input	A, B
$t_{\text{DDR IHD}}$	Data Hold Time of DDR Input	A, B
$t_{\text{DDRICLR2Q1}}$	Clear-to-Out Out_QR	C, D
$t_{\text{DDRICLR2Q2}}$	Clear-to-Out Out_QF	C, E
$t_{\text{DDRIREMCLR}}$	Clear Removal	C, B
$t_{\text{DDRIRECCLR}}$	Clear Recovery	C, B

Table 2-118 • RAM512X18
Automotive-Case Conditions: $T_J = 135^{\circ}\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$

Parameter	Description	–1	Std.	Units
t_{AS}	Address Setup Time	0.30	0.35	ns
t_{AH}	Address Hold Time	0.00	0.00	ns
t_{ENS}	REN, WEN Setup Time	0.11	0.13	ns
t_{ENH}	REN, WEN Hold Time	0.07	0.08	ns
t_{DS}	Input data (WD) Setup Time	0.22	0.26	ns
t_{DH}	Input data (WD) Hold Time	0.00	0.00	ns
t_{CKQ1}	Clock High to New Data Valid on RD (output retained)	2.58	3.03	ns
t_{CKQ2}	Clock High to New Data Valid on RD (pipelined)	1.07	1.26	ns
t_{C2CRWH}^1	Address collision clk-to-clk delay for reliable read access after write on same address—Applicable to Opening Edge	0.43	0.50	ns
t_{C2CWRH}^1	Address collision clk-to-clk delay for reliable write access after read on same address—Applicable to Opening Edge	0.50	0.59	ns
t_{RSTBQ}	RESET Low to Data Out Low on RD (flow-through)	1.10	1.29	ns
	RESET Low to Data Out Low on RD (pipelined)	1.10	1.29	ns
$t_{REMRSTB}$	RESET Removal	0.34	0.40	ns
$t_{RECRSTB}$	RESET Recovery	1.79	2.10	ns
$t_{MPWRSTB}$	RESET Minimum Pulse Width	0.25	0.30	ns
t_{CYC}	Clock Cycle Time	3.85	4.53	ns
F_{MAX}	Maximum Frequency	255	217	MHz

Notes:

1. For more information, refer to the application note [Simultaneous Read-Write Operations in Dual-Port SRAM for Flash-Based cSoCs and FPGAs](#).
2. For specific junction temperature and voltage supply levels, refer to [Table 2-5 on page 2-5](#) for derating values.

Table 2-119 • RAM4K9
Automotive-Case Conditions: $T_J = 115^\circ\text{C}$, Worst Case $V_{CC} = 1.425\text{ V}$

Parameter	Description	–1	Std.	Units
t_{AS}	Address Setup Time	0.30	0.35	ns
t_{AH}	Address Hold Time	0.00	0.00	ns
t_{ENS}	REN, WEN Setup Time	0.17	0.20	ns
t_{ENH}	REN, WEN Hold Time	0.12	0.14	ns
t_{BKS}	BLK Setup Time	0.28	0.33	ns
t_{BKH}	BLK Hold Time	0.02	0.03	ns
t_{DS}	Input data (DIN) Setup Time	0.22	0.26	ns
t_{DH}	Input data (DIN) Hold Time	0.00	0.00	ns
t_{CKQ1}	Clock High to New Data Valid on DOUT (output retained, WMODE = 0)	2.13	2.50	ns
	Clock High to New Data Valid on DOUT (flow-through, WMODE = 1)	2.81	3.30	ns
t_{CKQ2}	Clock High to New Data Valid on DOUT (pipelined)	1.07	1.25	ns
t_{C2CWWL}^1	Address collision clk-to-clk delay for reliable write after write on same address—Applicable to Closing Edge	0.28	0.33	ns
t_{C2CWWH}^1	Address collision clk-to-clk delay for reliable write after write on same address—Applicable to Rising Edge	0.26	0.30	ns
t_{C2CRWH}^1	Address collision clk-to-clk delay for reliable read access after write on same address—Applicable to Opening Edge	0.38	0.45	ns
t_{C2CWRH}^1	Address collision clk-to-clk delay for reliable write access after read on same address—Applicable to Opening Edge	0.42	0.49	ns
t_{RSTBQ}	RESET Low to Data Out Low on DOUT (flow-through)	1.10	1.29	ns
	RESET Low to Data Out Low on DOUT (pipelined)	1.10	1.29	ns
$t_{REMRSTB}$	RESET Removal	0.34	0.40	ns
$t_{RECRSTB}$	RESET Recovery	1.79	2.10	ns
$t_{MPWRSTB}$	RESET Minimum Pulse Width	0.25	0.30	ns
t_{CYC}	Clock Cycle Time	3.85	4.53	ns
F_{MAX}	Maximum Frequency	260	221	MHz

Notes:

1. For more information, refer to the application note [Simultaneous Read-Write Operations in Dual-Port SRAM for Flash-Based cSoCs and FPGAs](#).
2. For specific junction temperature and voltage supply levels, refer to [Table 2-5 on page 2-5](#) for derating values.

FIFO

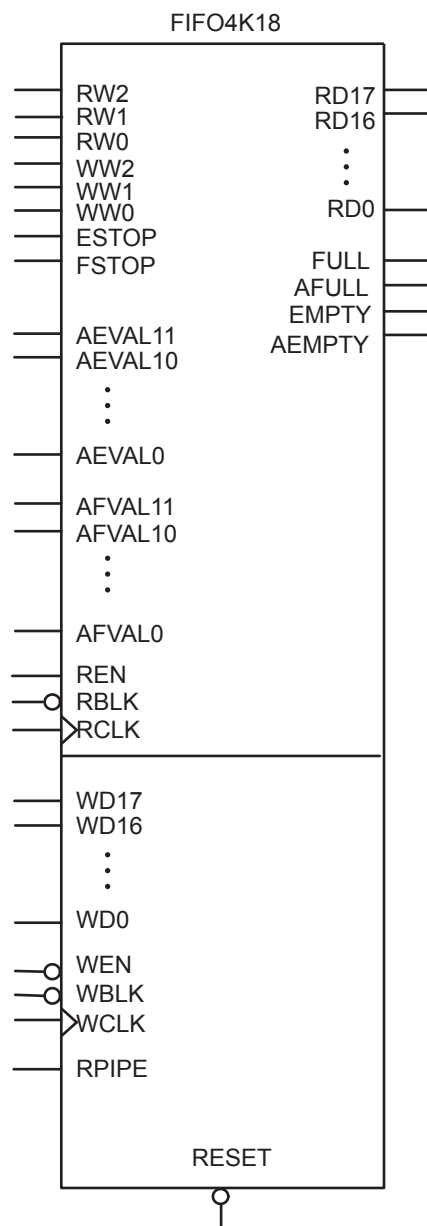
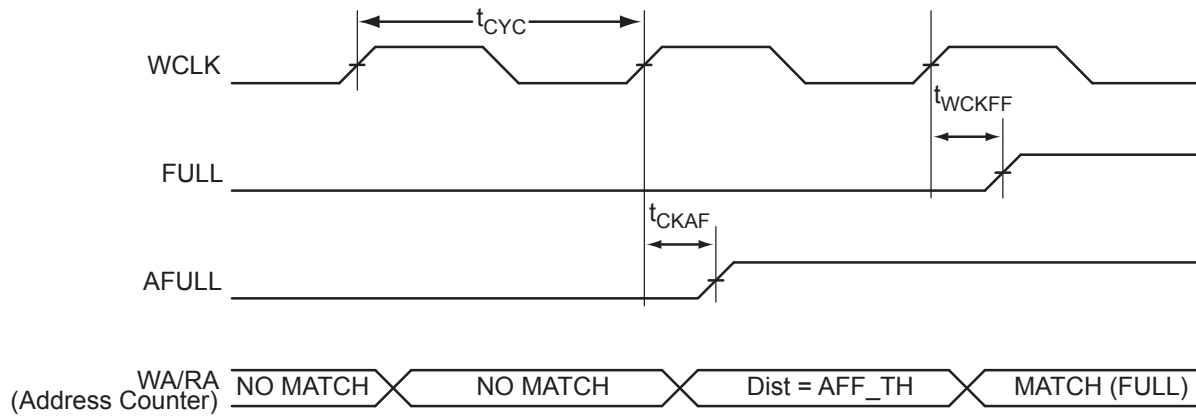
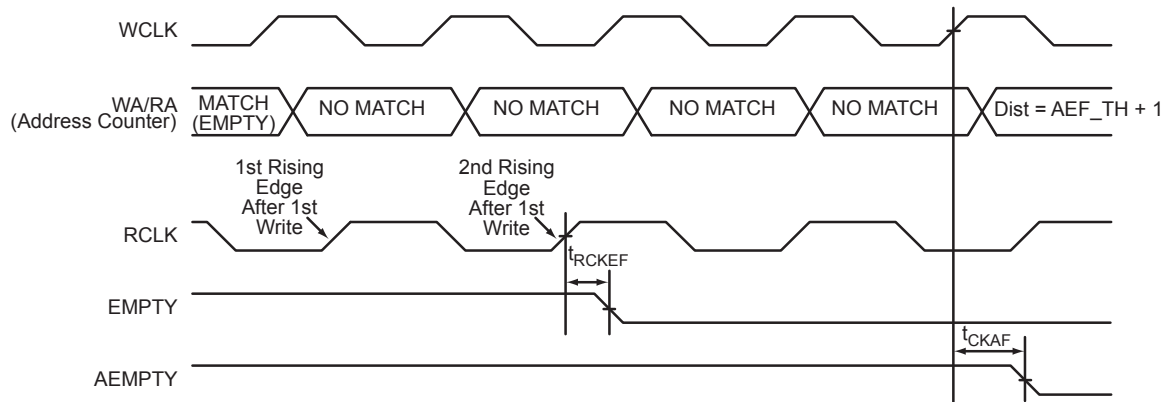
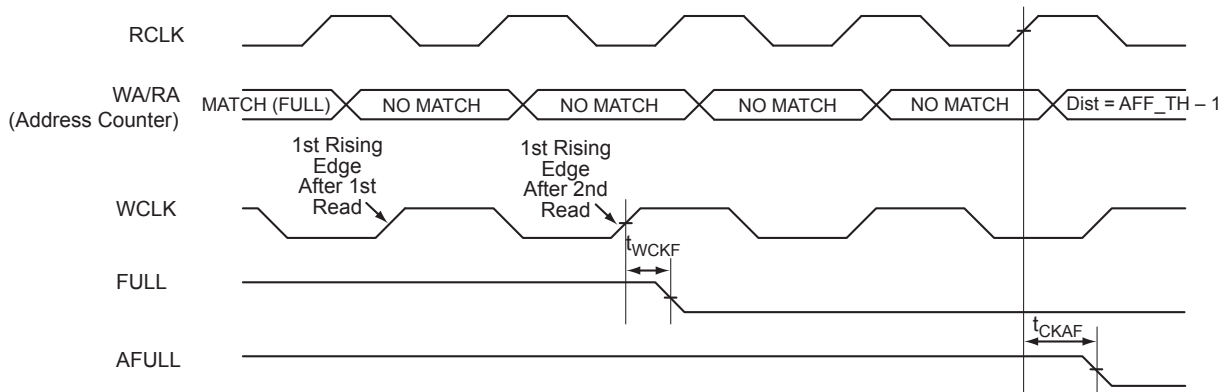
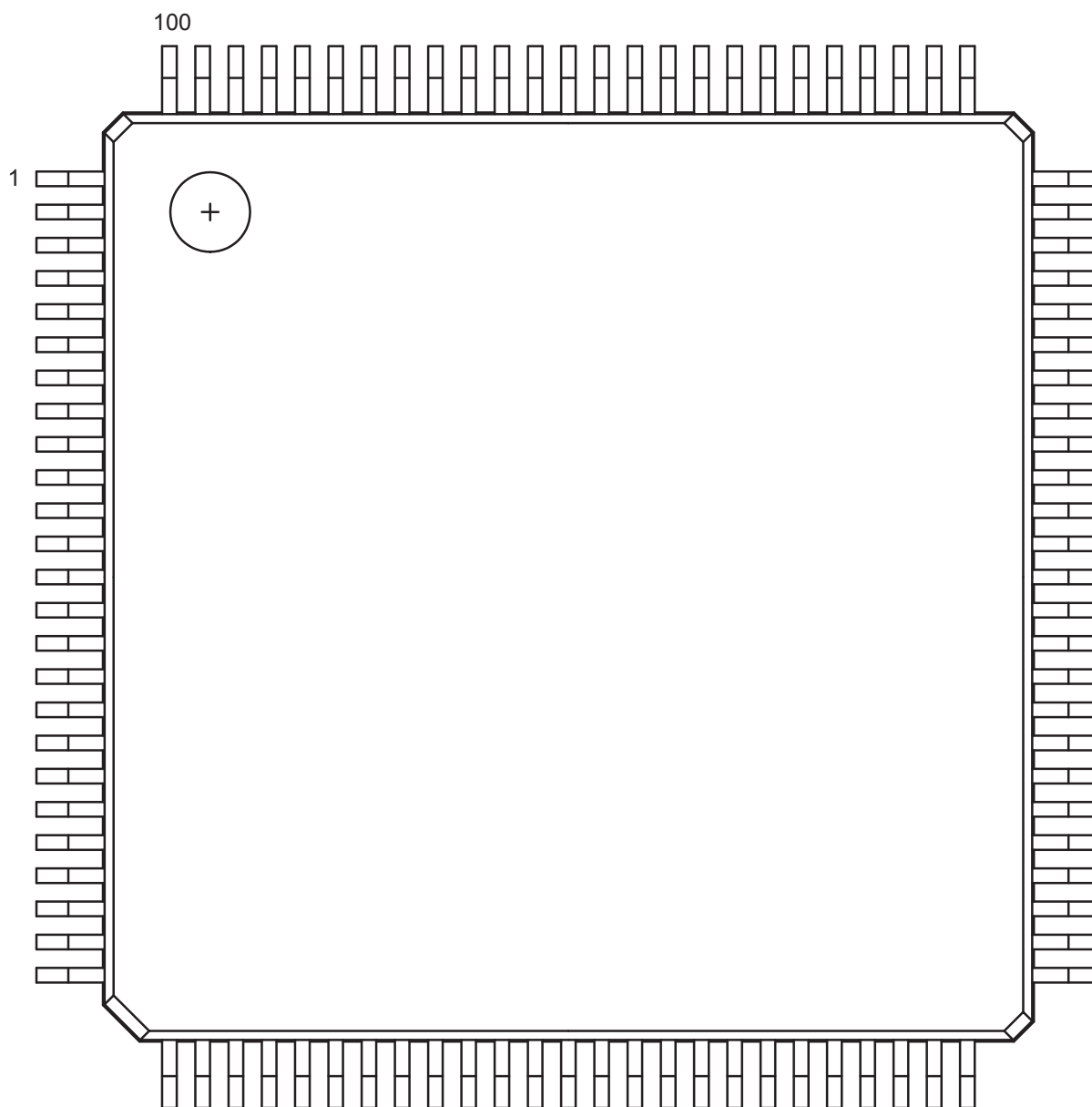


Figure 2-36 • FIFO Model


Figure 2-41 • FIFO FULL Flag and AFULL Flag Assertion

Figure 2-42 • FIFO EMPTY Flag and AEMPTY Flag Deassertion

Figure 2-43 • FIFO FULL Flag and AFULL Flag Deassertion

4 – Package Pin Assignments

VQ100



Note: This is the top view of the package.

Note

For Package Manufacturing and Environmental information, visit the Resource Center at <http://www.actel.com/products/solutions/package/docs.aspx>.

FG144	
Pin Number	A3P125 Function
A1	GNDQ
A2	VMV0
A3	GAB0/IO02RSB0
A4	GAB1/IO03RSB0
A5	IO11RSB0
A6	GND
A7	IO18RSB0
A8	VCC
A9	IO25RSB0
A10	GBA0/IO39RSB0
A11	GBA1/IO40RSB0
A12	GNDQ
B1	GAB2/IO69RSB1
B2	GND
B3	GAA0/IO00RSB0
B4	GAA1/IO01RSB0
B5	IO08RSB0
B6	IO14RSB0
B7	IO19RSB0
B8	IO22RSB0
B9	GBB0/IO37RSB0
B10	GBB1/IO38RSB0
B11	GND
B12	VMV0
C1	IO132RSB1
C2	GFA2/IO120RSB1
C3	GAC2/IO131RSB1
C4	VCC
C5	IO10RSB0
C6	IO12RSB0
C7	IO21RSB0
C8	IO24RSB0
C9	IO27RSB0
C10	GBA2/IO41RSB0
C11	IO42RSB0
C12	GBC2/IO45RSB0

FG144	
Pin Number	A3P125 Function
D1	IO128RSB1
D2	IO129RSB1
D3	IO130RSB1
D4	GAA2/IO67RSB1
D5	GAC0/IO04RSB0
D6	GAC1/IO05RSB0
D7	GBC0/IO35RSB0
D8	GBC1/IO36RSB0
D9	GBB2/IO43RSB0
D10	IO28RSB0
D11	IO44RSB0
D12	GCB1/IO53RSB0
E1	VCC
E2	GFC0/IO125RSB1
E3	GFC1/IO126RSB1
E4	VCCIB1
E5	IO68RSB1
E6	VCCIB0
E7	VCCIB0
E8	GCC1/IO51RSB0
E9	VCCIB0
E10	VCC
E11	GCA0/IO56RSB0
E12	IO46RSB0
F1	GFB0/IO123RSB1
F2	VCOMPLF
F3	GFB1/IO124RSB1
F4	IO127RSB1
F5	GND
F6	GND
F7	GND
F8	GCC0/IO52RSB0
F9	GCB0/IO54RSB0
F10	GND
F11	GCA1/IO55RSB0
F12	GCA2/IO57RSB0

FG144	
Pin Number	A3P125 Function
G1	GFA1/IO121RSB1
G2	GND
G3	VCCPLF
G4	GFA0/IO122RSB1
G5	GND
G6	GND
G7	GND
G8	GDC1/IO61RSB0
G9	IO48RSB0
G10	GCC2/IO59RSB0
G11	IO47RSB0
G12	GCB2/IO58RSB0
H1	VCC
H2	GFB2/IO119RSB1
H3	GFC2/IO118RSB1
H4	GEC1/IO112RSB1
H5	VCC
H6	IO50RSB0
H7	IO60RSB0
H8	GDB2/IO71RSB1
H9	GDC0/IO62RSB0
H10	VCCIB0
H11	IO49RSB0
H12	VCC
J1	GEB1/IO110RSB1
J2	IO115RSB1
J3	VCCIB1
J4	GEC0/IO111RSB1
J5	IO116RSB1
J6	IO117RSB1
J7	VCC
J8	TCK
J9	GDA2/IO70RSB1
J10	TDO
J11	GDA1/IO65RSB0
J12	GDB1/IO63RSB0

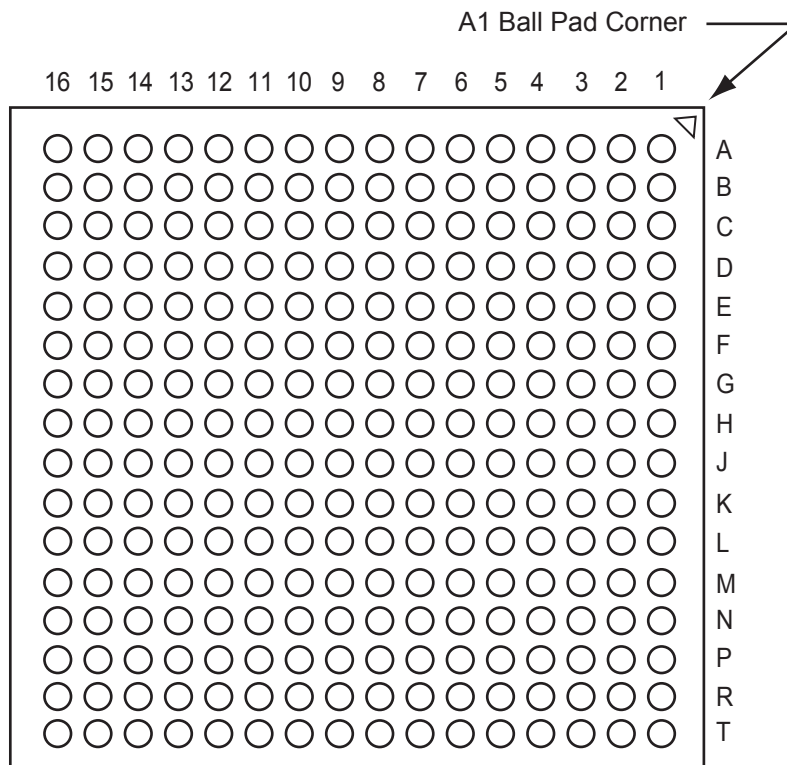
FG144	
Pin Number	A3P250 Function
K1	GEB0/IO99NDB3
K2	GEA1/IO98PDB3
K3	GEA0/IO98NDB3
K4	GEA2/IO97RSB2
K5	IO90RSB2
K6	IO84RSB2
K7	GND
K8	IO66RSB2
K9	GDC2/IO63RSB2
K10	GND
K11	GDA0/IO60VDB1
K12	GDB0/IO59VDB1
L1	GND
L2	VMV3
L3	GEB2/IO96RSB2
L4	IO91RSB2
L5	VCCIB2
L6	IO82RSB2
L7	IO80RSB2
L8	IO72RSB2
L9	TMS
L10	VJTAG
L11	VMV2
L12	TRST
M1	GNDQ
M2	GEC2/IO95RSB2
M3	IO92RSB2
M4	IO89RSB2
M5	IO87RSB2
M6	IO85RSB2
M7	IO78RSB2
M8	IO76RSB2
M9	TDI
M10	VCCIB2
M11	VPUMP
M12	GNDQ

FG144	
Pin Number	A3P1000 Function
A1	GNDQ
A2	VMV0
A3	GAB0/IO02RSB0
A4	GAB1/IO03RSB0
A5	IO10RSB0
A6	GND
A7	IO44RSB0
A8	VCC
A9	IO69RSB0
A10	GBA0/IO76RSB0
A11	GBA1/IO77RSB0
A12	GNDQ
B1	GAB2/IO224PDB3
B2	GND
B3	GAA0/IO00RSB0
B4	GAA1/IO01RSB0
B5	IO13RSB0
B6	IO26RSB0
B7	IO35RSB0
B8	IO60RSB0
B9	GBB0/IO74RSB0
B10	GBB1/IO75RSB0
B11	GND
B12	VMV1
C1	IO224NDB3
C2	GFA2/IO206PPB3
C3	GAC2/IO223PDB3
C4	VCC
C5	IO16RSB0
C6	IO29RSB0
C7	IO32RSB0
C8	IO63RSB0
C9	IO66RSB0
C10	GBA2/IO78PDB1
C11	IO78NDB1
C12	GBC2/IO80PPB1

FG144	
Pin Number	A3P1000 Function
D1	IO213PDB3
D2	IO213NDB3
D3	IO223NDB3
D4	GAA2/IO225PPB3
D5	GAC0/IO04RSB0
D6	GAC1/IO05RSB0
D7	GBC0/IO72RSB0
D8	GBC1/IO73RSB0
D9	GBB2/IO79PDB1
D10	IO79NDB1
D11	IO80NPB1
D12	GCB1/IO92PPB1
E1	VCC
E2	GFC0/IO209NDB3
E3	GFC1/IO209PDB3
E4	VCCIB3
E5	IO225NPB3
E6	VCCIB0
E7	VCCIB0
E8	GCC1/IO91PDB1
E9	VCCIB1
E10	VCC
E11	GCA0/IO93NDB1
E12	IO94NDB1
F1	GFB0/IO208NPB3
F2	VCOMPLF
F3	GFB1/IO208PPB3
F4	IO206NPB3
F5	GND
F6	GND
F7	GND
F8	GCC0/IO91NDB1
F9	GCB0/IO92NPB1
F10	GND
F11	GCA1/IO93PDB1
F12	GCA2/IO94PDB1

FG144	
Pin Number	A3P1000 Function
G1	GFA1/IO207PPB3
G2	GND
G3	VCCPLF
G4	GFA0/IO207NPB3
G5	GND
G6	GND
G7	GND
G8	GDC1/IO111PPB1
G9	IO96NDB1
G10	GCC2/IO96PDB1
G11	IO95NDB1
G12	GCB2/IO95PDB1
H1	VCC
H2	GFB2/IO205PDB3
H3	GFC2/IO204PSB3
H4	GEC1/IO190PDB3
H5	VCC
H6	IO105PDB1
H7	IO105NDB1
H8	GDB2/IO115RSB2
H9	GDC0/IO111NPB1
H10	VCCIB1
H11	IO101PSB1
H12	VCC
J1	GEB1/IO189PDB3
J2	IO205NDB3
J3	VCCIB3
J4	GEC0/IO190NDB3
J5	IO160RSB2
J6	IO157RSB2
J7	VCC
J8	TCK
J9	GDA2/IO114RSB2
J10	TDO
J11	GDA1/IO113PDB1
J12	GDB1/IO112PDB1

FG256



Note: This is the bottom view of the package.

Note

For Package Manufacturing and Environmental information, visit the Resource Center at <http://www.actel.com/products/solutions/package/docs.aspx>.

FG256		FG256		FG256	
Pin Number	A3P1000 Function	Pin Number	A3P1000 Function	Pin Number	A3P1000 Function
A1	GND	C5	GAC0/IO04RSB0	E9	IO47RSB0
A2	GAA0/IO00RSB0	C6	GAC1/IO05RSB0	E10	VCCIB0
A3	GAA1/IO01RSB0	C7	IO25RSB0	E11	VCCIB0
A4	GAB0/IO02RSB0	C8	IO36RSB0	E12	VMV1
A5	IO16RSB0	C9	IO42RSB0	E13	GBC2/IO80PDB1
A6	IO22RSB0	C10	IO49RSB0	E14	IO83PPB1
A7	IO28RSB0	C11	IO56RSB0	E15	IO86PPB1
A8	IO35RSB0	C12	GBC0/IO72RSB0	E16	IO87PDB1
A9	IO45RSB0	C13	IO62RSB0	F1	IO217NDB3
A10	IO50RSB0	C14	VMV0	F2	IO218NDB3
A11	IO55RSB0	C15	IO78NDB1	F3	IO216PDB3
A12	IO61RSB0	C16	IO81NDB1	F4	IO216NDB3
A13	GBB1/IO75RSB0	D1	IO222NDB3	F5	VCCIB3
A14	GBA0/IO76RSB0	D2	IO222PDB3	F6	GND
A15	GBA1/IO77RSB0	D3	GAC2/IO223PDB3	F7	VCC
A16	GND	D4	IO223NDB3	F8	VCC
B1	GAB2/IO224PDB3	D5	GNDQ	F9	VCC
B2	GAA2/IO225PDB3	D6	IO23RSB0	F10	VCC
B3	GNDQ	D7	IO29RSB0	F11	GND
B4	GAB1/IO03RSB0	D8	IO33RSB0	F12	VCCIB1
B5	IO17RSB0	D9	IO46RSB0	F13	IO83NPB1
B6	IO21RSB0	D10	IO52RSB0	F14	IO86NPB1
B7	IO27RSB0	D11	IO60RSB0	F15	IO90PPB1
B8	IO34RSB0	D12	GNDQ	F16	IO87NDB1
B9	IO44RSB0	D13	IO80NDB1	G1	IO210PSB3
B10	IO51RSB0	D14	GBB2/IO79PDB1	G2	IO213NDB3
B11	IO57RSB0	D15	IO79NDB1	G3	IO213PDB3
B12	GBC1/IO73RSB0	D16	IO82NSB1	G4	GFC1/IO209PPB3
B13	GBB0/IO74RSB0	E1	IO217PDB3	G5	VCCIB3
B14	IO71RSB0	E2	IO218PDB3	G6	VCC
B15	GBA2/IO78PDB1	E3	IO221NDB3	G7	GND
B16	IO81PDB1	E4	IO221PDB3	G8	GND
C1	IO224NDB3	E5	VMV0	G9	GND
C2	IO225NDB3	E6	VCCIB0	G10	GND
C3	VMV3	E7	VCCIB0	G11	VCC
C4	IO11RSB0	E8	IO38RSB0	G12	VCCIB1

